



VMDSEMI

**VUPB003R090NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
30V	9mΩ@10V	25A
	13mΩ@4.5V	

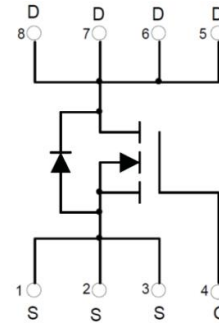
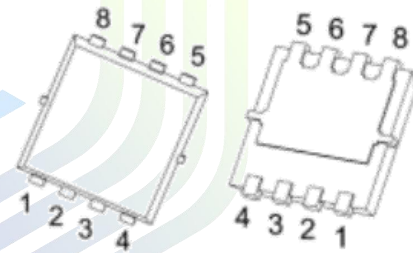


Figure 1 Symbol of VUPB003R090NA

## Features

- Trench Technology Power MOSFET
- Low Gate Charge
- Low Gate Resistance
- Low  $R_{DS(ON)}$
- 100% UIS Tested

## Package Type



## PDFN5X6-8L

## Application

- Power Switch
- Battery protection applications
- Synchronous Rectification

Figure 2 Package Type of VUPB003R090NA

## Ordering Information

Product Name	Package
VUPB003R090NA	PDFN5X6-8L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	25	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	100	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	61	mJ
Avalanche Current <sup>Note3</sup>	$I_{AS}$	35	A
Total Power Dissipation <sup>Note5</sup>	$P_D$	25	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		50		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		5		°C/W

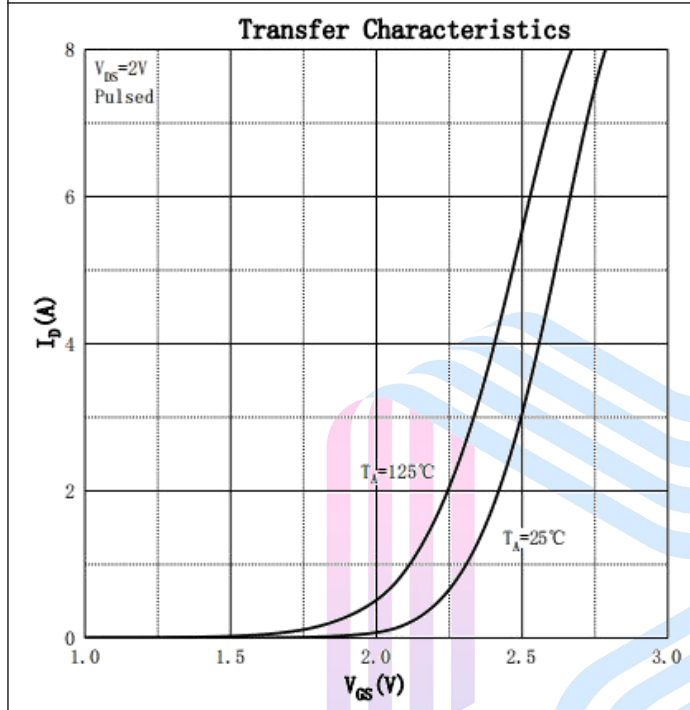
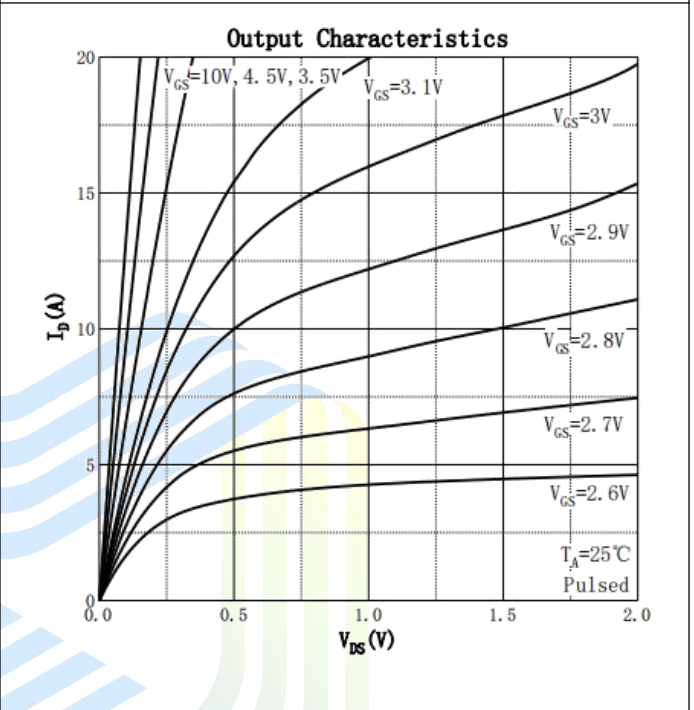
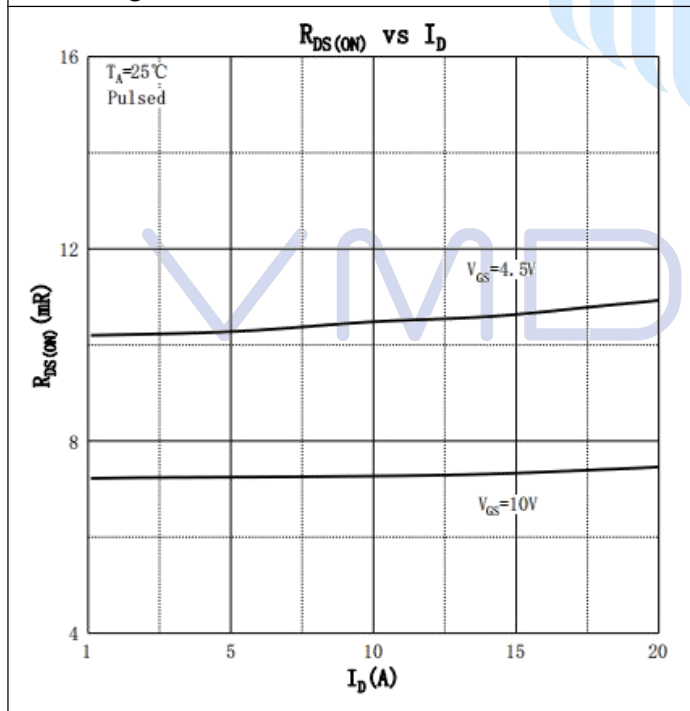
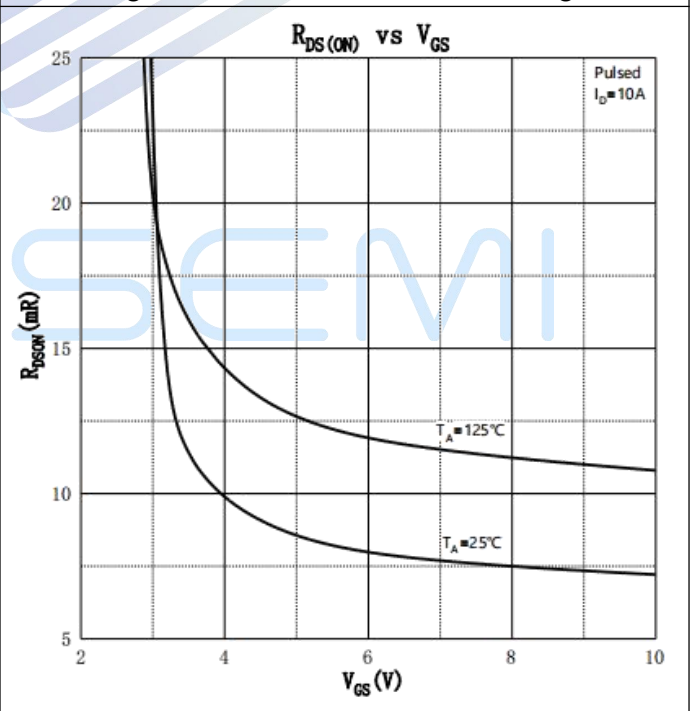
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

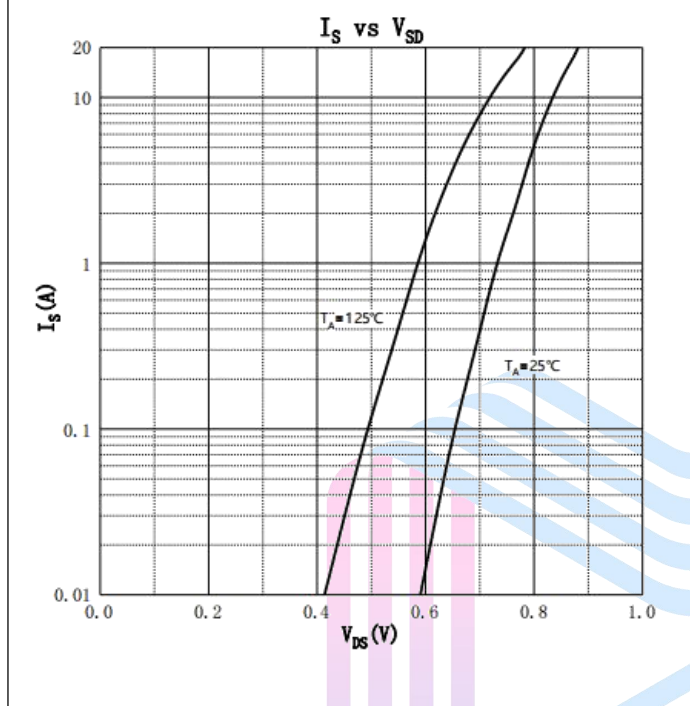
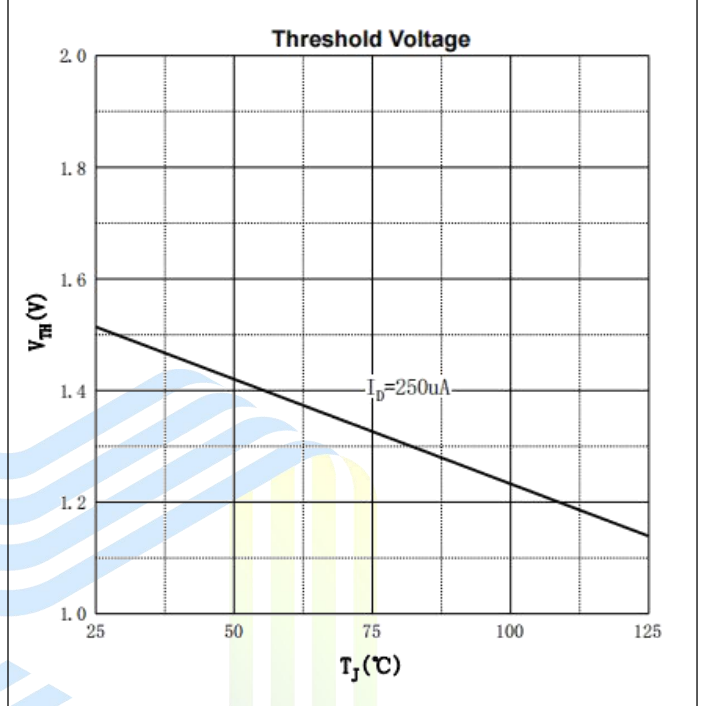
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=24V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	3	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=15A$		7.3	9	mΩ
		$V_{GS}=4.5V, I_D=12A$		10.5	13	
Forward Transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=5V, I_D=10A$		15		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=15V$		1217		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		141		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		129		pF
Total Gate Charge	$Q_g$	$V_{DS}=15V$		21		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		3.2		
Gate-Drain Charge	$Q_{gd}$	$I_D=10A$		5.6		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		2		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$		6.5		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		5.2		
Turn-off Delay Time	$t_{d(off)}$	$R_L=1.5\Omega$		20		
Turn-off Fall Time	$t_f$	$R_{GEN}=3\Omega$		4.5		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=3A$			1.2	V

Notes :

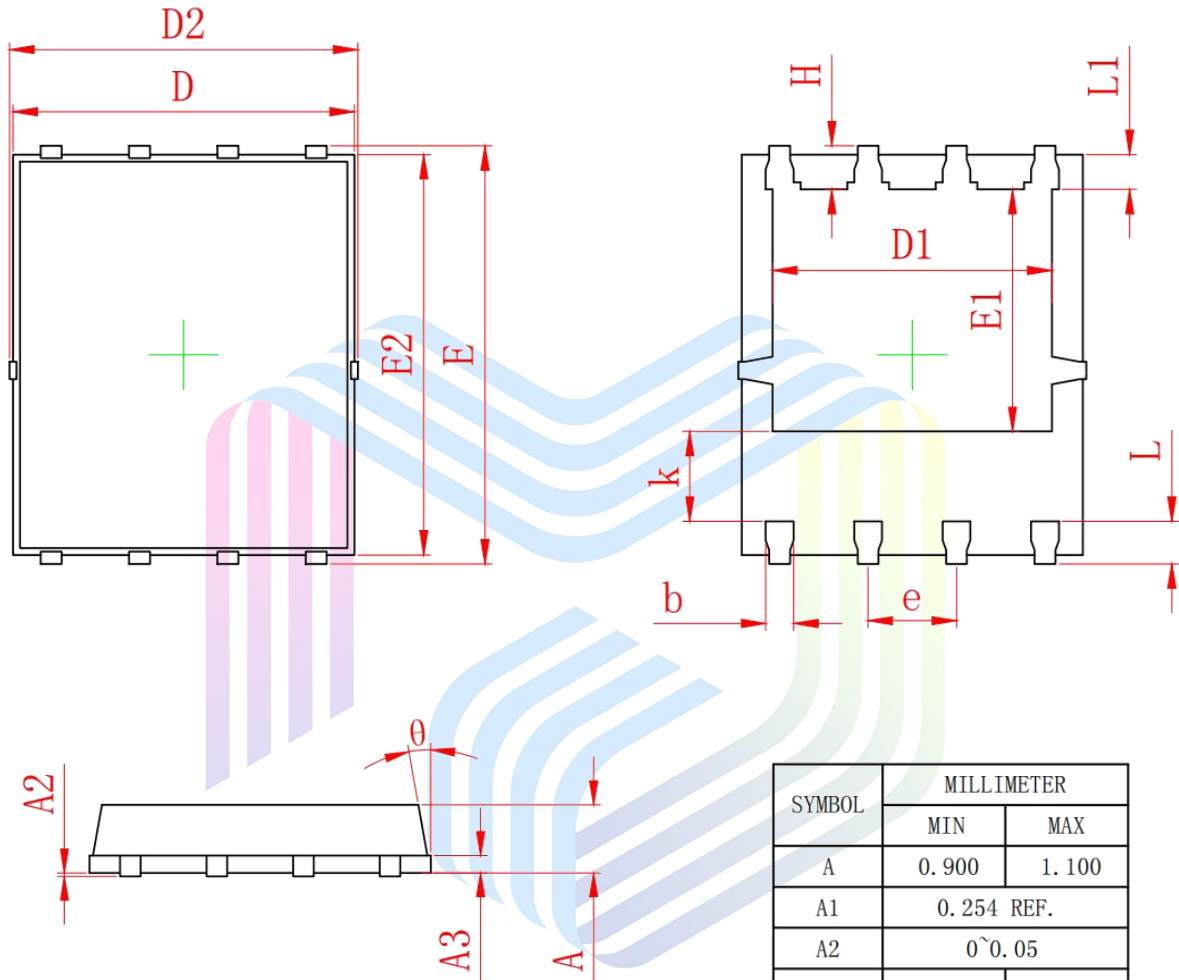
1. The maximum current rating is limited by package. And device mounted on a large heatsink
2. Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
3. EAS condition:  $V_{DD}=15V, V_{GS}=10V, L=0.1mH, R_G=25\Omega$  Starting  $T_J=25^\circ C$ .
4. Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. The power dissipation  $P_D$  is limited by  $T_{J(MAX)}=150^\circ C$ . And device mounted on a large heatsink
6. Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ .

## Typical Performance Characteristics

**Figure 3: Transfer Characteristics**

**Figure 4: Output Characteristics**

**Figure 5: On-Resistance vs. Drain Current**

**Figure 6: On-Resistance vs. Gate Voltage**


**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**


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**Mechanical Dimensions:**
**PDFN5X6-8L Package Information**


SYMBOL	MILLIMETER	
	MIN	MAX
A	0.900	1.100
A1	0.254 REF.	
A2	0 <sup>~</sup> 0.05	
D	4.824	4.976
D1	3.910	4.110
D2	4.944	5.076
E	5.924	6.076
E1	3.375	3.575
E2	5.674	5.826
b	0.350	0.450
e	1.270 TYP.	
L	0.534	0.686
L1	0.424	0.576
k	1.190	1.390
H	0.549	0.701
θ	8°	12°



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